MEMORY MODULE

IR-X 2800 D4 64 L16 S 8G

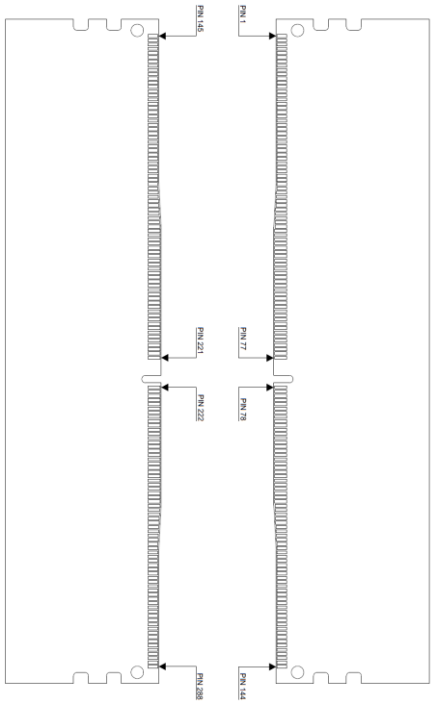
- IR-X — IRDM X
- 2800 — SPEED / DATA TRANSFER 2800Mhz / PC4-22400
- D4 — MODULE TYPE DDR4 SDRAM DIMM
- 64 — MODULE DATA WIDTH 64
- L16 — CAS LATENCY 16
- S — SINGLE RANK
- 8G — MODULE DENSITY 8GB

DDRIV MODULE PART NUMBERING SYSTEM



FEATURES

PART NUMBER	IR-X2800D464L16S/8G
MODULE TYPE	DDR4 SDRAM DIMM
MODULE DENSITY	8GB
MODULE DATA WIDTH	64
DRAM COMPONENT ORAGNIZATION	1024Mx8
NUMBER OF DRAM COMPONENTS	8
NUMBER OF MODULE RANKS	1
NUMBER OF MODULE SIDES	1
REGISTERED	NO
ECC SUPPORT	NO
PIN COUNT	288 PIN
SUPPLY VOLTAGE	1,20V-1,25V
INTERFACE	PSEUDO OPEN DRAIN 1.2V (POD12)

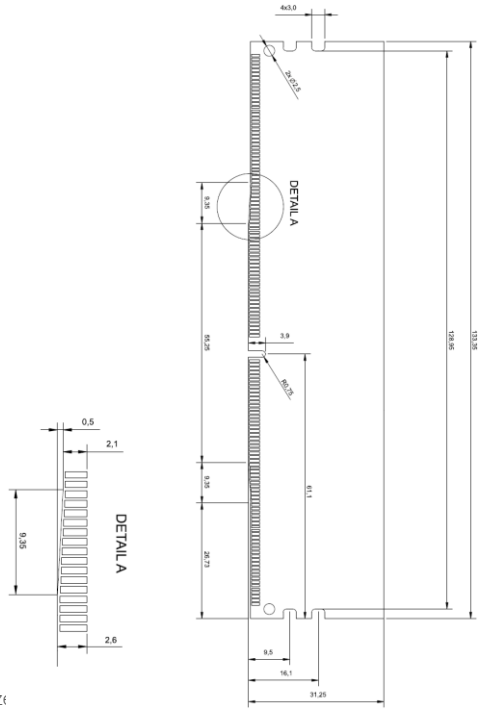


DYNAMIC PARAMETERS

CAS LATENCY	16
RAS# TO CAS# DELAY, tRCD	18
ROW PRECHARGE TIME, tRP	18
ACTIVE TO PRECHARGE TIME, tRAS	35

PCB DETAILS

PCB TYPE	DDR4 SDRAM DIMM
BOARD DIMENSIONS	133,35 x 31,25mm ± 0,1mm
BOARD THICKNESS	1,4mm ± 0,1mm
DRAM PACKAGE INFORMATION	FBGA, x8bit
CONTACT PADS (PIN)	GOLD PLATED



GOODRAM zastrzega prawo do zmian w specyfikacji i opisach produktu w każdej chwili bez uprz
Product Sheet | IRDM X | V1.0 | © Wilk Elektronik S.A. - GOODRAM

SPD CONFIGURATION

Byte	Description	HEX	DEC
0	Number of Serial PD Bytes Written / SPD Device Size / CRC Coverage 1 2	0x23	35
1	SPD Revision	0x10	16
2	Key Byte / DRAM Device Type	0x0c	12
3	Key Byte / Module Type	0x02	2
4	SDRAM Density and Banks	0x85	133
5	SDRAM Addressing	0x21	33
6	SDRAM Package Type	0x00	0
7	SDRAM Optional Features	0x08	8
8	SDRAM Thermal and Refresh Options	0x00	0
9	Other SDRAM Optional Features	0x00	0
10	Reserved -- must be coded as 0x00	0x00	0
11	Module Nominal Voltage, VDD	0x03	3
12	Module Organization	0x01	1
13	Module Memory Bus Width	0x03	3
14	Module Thermal Sensor	0x00	0
15	Extended module type	0x00	0
16	Reserved -- must be coded as 0x00	0x00	0
17	Timebases	0x00	0
18	SDRAM Minimum Cycle Time (tCKAVGmin)	0x08	8
19	SDRAM Maximum Cycle Time (tCKAVGmax)	0x0c	12
20	CAS Latencies Supported, First Byte	0xfc	252
21	CAS Latencies Supported, Second Byte	0x03	3
22	CAS Latencies Supported, Third Byte	0x00	0
23	CAS Latencies Supported, Fourth Byte	0x00	0
24	Minimum CAS Latency Time (tAAmin)	0x6c	108
25	Minimum RAS to CAS Delay Time (tRCDmin)	0x6c	108
26	Minimum Row Precharge Delay Time (tRPmin)	0x6c	108
27	Upper Nibbles for tRASmin and tRCmin	0x11	17
28	Minimum Active to Precharge Delay Time (tRASmin), Least Significant Byte	0x08	8
29	Minimum Active to Active/Refresh Delay Time (tRCmin), Least Significant Byte	0x74	116
30	Minimum Refresh Recovery Delay Time (tRFC1min), LSB	0xf0	240
31	Minimum Refresh Recovery Delay Time (tRFC1min), MSB	0x0a	10
32	Minimum Refresh Recovery Delay Time (tRFC2min), LSB	0x20	32
33	Minimum Refresh Recovery Delay Time (tRFC2min), MSB	0x08	8
34	Minimum Refresh Recovery Delay Time (tRFC4min), LSB	0x00	0
35	Minimum Refresh Recovery Delay Time (tRFC4min), MSB	0x05	5
36	Minimum Four Activate Window Time (tFAWmin), Most Significant Nibble	0x00	0
37	Minimum Four Activate Window Time (tFAWmin), Least Significant Byte	0xb8	184
38	Minimum Activate to Activate Delay Time (tRRD_Smin), different bank group	0x1e	30
39	Minimum Activate to Activate Delay Time (tRRD_Lmin), same bank group	0x2b	43
40	Minimum CAS to CAS Delay Time (tCCD_Lmin), same bank group	0x2b	43
41-59	Reserved -- must be coded as 0x00	0x00	0

GOODRAM zastrzega prawo do zmian w specyfikacji i opisach produktu w każdej chwili bez uprzedniej informacji.

SPD CONFIGURATION

Byte	Description	HEX	DEC
60	Connector to SDRAM Bit Mapping	0x16	22
61	Connector to SDRAM Bit Mapping	0x36	54
62	Connector to SDRAM Bit Mapping	0x16	22
63	Connector to SDRAM Bit Mapping	0x36	54
64	Connector to SDRAM Bit Mapping	0x16	22
65	Connector to SDRAM Bit Mapping	0x36	54
66	Connector to SDRAM Bit Mapping	0x16	22
67	Connector to SDRAM Bit Mapping	0x36	54
68	Connector to SDRAM Bit Mapping	0x00	0
69	Connector to SDRAM Bit Mapping	0x00	0
70	Connector to SDRAM Bit Mapping	0x16	22
71	Connector to SDRAM Bit Mapping	0x36	54
72	Connector to SDRAM Bit Mapping	0x16	22
73	Connector to SDRAM Bit Mapping	0x36	54
74	Connector to SDRAM Bit Mapping	0x16	22
75	Connector to SDRAM Bit Mapping	0x36	54
76	Connector to SDRAM Bit Mapping	0x16	22
77	Connector to SDRAM Bit Mapping	0x36	54
78-116	Reserved -- must be coded as 0x00	0x00	0
117	Fine Offset for Minimum CAS to CAS Delay Time (tCCD_Lmin), same bank group	0xed	237
118	Fine Offset for Minimum Activate to Activate Delay Time (tRRD_Lmin), same bank group	0xb5	181
119	Fine Offset for Minimum Activate to Activate Delay Time (tRRD_Smin), different bank group	0xcf	207
120	Fine Offset for Minimum Activate to Activate/Refresh Delay Time (tRCmin)	0x00	0
121	Fine Offset for Minimum Row Precharge Delay Time (tRPmin)	0x00	0
122	Fine Offset for Minimum RAS to CAS Delay Time (tRCDmin)	0x00	0
123	Fine Offset for Minimum CAS Latency Time (tAAmin)	0x00	0
124	Fine Offset for SDRAM Maximum Cycle Time (tCKAVGmax)	0x00	0
125	Fine Offset for SDRAM Minimum Cycle Time (tCKAVGmin)	0xc2	194
126	CRC for Base Configuration Section, Least Significant Byte	0x00	0
127	CRC for Base Configuration Section, Most Significant Byte	0xbd	189
128-511	Module Specific SPD Bytes		

GOODRAM zastrzega prawo do zmian w specyfikacji i opisach produktu w każdej chwili bez uprzedniej informacji.